


## Full Material Declaration for attached parts list

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	<p><b>Diotec Semiconductor AG</b>  <b>DUNS number:</b> 330866844          -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany  <b>Declarations authorised by:</b>          Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 1 May 2009 [Approved on 25 February 2016, 14:49 GMT]

## Materials and substances

Use/Location	Material group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.40000%	Nickel	7440-02-0	0.95000%
			Gold	7440-57-5	10.95000%
			Polydimethylsiloxane rubber	63394-02-5	25.20000%
			Silicon	7440-21-3	62.90000%
Die attach	Lead and Lead alloys	0.20000%	Silver	7440-22-4	1.50000%
			Tin	7440-31-5	5.29700%
			Lead	7439-92-1	93.20300%
Encapsulation	EP (Epoxy resin)	44.90000%	Carbon black	1333-86-4	0.30000%
			ANTIMONY TRIOXIDE	1309-64-4	0.80000%
			Tetrabromobisphenol A (TBBPA)	79-94-7	0.99000%
			Epoxy resin 89	26335-32-0	27.61000%
			Quartz sand	60676-86-0	70.30000%
Leadfinish	Tin plating	2.20000%	Tin	7440-31-5	100.00000%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	52.30000%	Copper	7440-50-8	100.00000%

## Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
D 8 x 7.5	Diode axial	1.3	g